	e standard								
Operating		-55 °C to +10	5°C (Note1)	Storage		-10 °C	to +60°C (N	lote3)	
	temperature ran Operating	ige	. ,	temperature Storage	e range				
Rating	humidity range	20% to 80%	6 (Note2)	humidity rar	nge	40%	o to 70% (№	Note3)	
	Applicable co	nnector DF63-3S-3.	96C	Voltage			AC/DC 630V	-	
			Cur		rrent		AWG #16 : 15A		
						AWG #18 : 13A AWG #20 : 11A			
		Rated Voltage	Rated Curr				AWG #22 : 9A		
		600V AC/DC			Overvoltage Category IP-De		-		
		300V AC/DC	e	I IPOC)		
	-		Specificat	ions					
	4		•		Dec			ОТ	۸ - T
	tem	Test metho	d		Red	quirements		QT	AT
Construction General examination		Visually and by measuring instrument.							V
		Visually and by measuring instrument.			According to drawing.				Х
Marking		Confirmed visually.						Х	Х
Electric c	haracterist								
Contact resis				10 m(2 MAX.			Х	_
		20mV MAX, 1mA (DC or 1000Hz).							
Insulation resistance		500 V DC.			1000 MΩ MIN.				-
Voltage proof		1500 V AC for 1 min.			No flashover or breakdown.				_
Mechani	cal charact	eristics							
Vibration		30 times insertion and extraction.			①Contact resistance: 20 m Ω MAX.			Х	—
					②No damage, crack or looseness of parts.				
		Frequency 10 to 55 Hz, single amplitude			①No electrical discontinuity of 1 μ s.			Х	_
		0.75 mm, at 10 cycles for 3 direction. 490 m/s ² duration of pulse 11 ms at 3 times each for 3 both			 ②No damage, crack or looseness of parts. ①No electrical discontinuity of 1 µ s. 			X	
		axial directions.			(2)No damage, crack or looseness of parts.			^	_
Environm	ental charac			ENU	damage, crack or		anto.		
Damp heat		Exposed at 40 \pm 2°C , 90 to 95 %,	96 h	(1)Cor	ntact resistance: 2	20 m Q MAX		Х	_
(Steady state)		(After leaving the room temperature for			(2) Insulation resistance: 500 M Ω MIN.				
		1-2h.)			No damage, crack or looseness of parts.				
Rapid change of temperature		Temperature -55°C→ +85°C			①Contact resistance: 20 m Ω MAX.			Х	—
		Time 30min→ 30min			(2) Insulation resistance: 1000 M Ω MIN.				
		Under 5 cycles. (The transferring time of the tank is 2-3 min)			(3)No damage, crack or looseness of parts.				
		(After leaving the room temperature for							
		1) Automatic soldering (Flow)			No deformation of case of excessive looseness of the terminals.				
Soldering heat		Soldered at solder temperature, 260°c for in immersion , duration, 10 s.							-
		Soldering from temperature :300 Soldering time :3s.	С,						
		No strength on contact.				A new uniform coating of solder shall cover			
Solderability		Soldered at solder temperature,				-		14	-
		Soldered at solder temperature, 245°c for in immersion, duration, s	5 s.		v uniform coating num of 95 % of t	-		Х	
Note 1: Inclu		Soldered at solder temperature,	5 s.			-		X	
Note 1: Inclu Note 2: No c Note3: Apply t	condensing to the condition o	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc	ts before mounted	minin	num of 95 % of t	he surface b	eing immersed.	X	
Note 1: Inclu Note 2: No c Note3: Apply t	condensing to the condition o	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current.	ts before mounted	minin	num of 95 % of t	he surface b	eing immersed.	X	
Note 1: Inclu Note 2: No c Note3: Apply t After m	condensing to the condition o ounted on PCB b	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc poard , operating temperature and hun	ts before mounted	d on PCB.	num of 95 % of t	he surface b	eing immersed.		
Note 1: Inclu Note 2: No c Note3: Apply t After m	condensing to the condition o ounted on PCB b	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc poard , operating temperature and hum Description of revisions	ts before mounter nidity range is app	minin d on PCB. Died for interim Designed	num of 95 % of t	he surface b ransportation Chec	eing immersed. ked	Da	ate
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun	condensing to the condition o ounted on PCB b	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc poard , operating temperature and hun	ts before mounter nidity range is app	d on PCB.	num of 95 % of t	he surface b ransportation Chec SZ. (eing immersed. ked N0	Da 18. 0	9. 20
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun	condensing to the condition o ounted on PCB b	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc poard , operating temperature and hum Description of revisions	ts before mounter nidity range is app	minin d on PCB. Died for interim Designed	aum of 95 % of t	he surface b ransportation Chec SZ. (HS	eing immersed. ked NO . OKAWA	Da 18. 0 17. 0	9. 20 2. 14
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun	condensing to the condition o ounted on PCB b	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc poard , operating temperature and hum Description of revisions	ts before mounter nidity range is app	minin d on PCB. Died for interim Designed	Approved Checked	he surface b ransportation Chec SZ. (HS TS. F	eing immersed. ked NO . OKAWA UKUSHIMA	Da 18.0 17.0 17.0	9. 20 2. 14 2. 14
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun 1 2 Remarks	to the condition o counted on PCB t	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc board , operating temperature and hun Description of revisions DIS-H-00004228	ts before mounter nidity range is app	minin d on PCB. Died for interim Designed	Approved Checked Designed	ransportation Chec SZ. (HS TS. F YK. Y	eing immersed. ked NO . OKAWA UKUSHIMA AMAGUCHI	Da 18.0 17.0 17.0 17.0	9. 20 2. 14 2. 14 2. 14
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun 1 2 Remarks	to the condition o counted on PCB t	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc poard , operating temperature and hum Description of revisions	ts before mounter nidity range is app	minin d on PCB. Died for interim Designed	Approved Checked	he surface b ransportation Chec SZ. C HS TS. F YK. Y YK. Y	eing immersed. ked NO . OKAWA UKUSHIMA AMAGUCHI AMAGUCHI	Da 18. 0 17. 0 17. 0 17. 0	9. 20 2. 14 2. 14 2. 13 2. 13
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun Coun Remarks	condensing to the condition o counted on PCB to t	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc board , operating temperature and hun Description of revisions DIS-H-00004228	ts before mounten hidity range is app	d on PCB. Ilied for interim Designed TS. KUMAZAWA	Approved Checked Designed	he surface b ransportation Chec SZ. C HS TS. F YK. Y YK. Y	eing immersed. ked NO . OKAWA UKUSHIMA AMAGUCHI	Da 18. 0 17. 0 17. 0 17. 0	9. 20 2. 14 2. 14 2. 13 2. 13
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun 1 2 Remarks Unless other Note QT:Q	condensing to the condition o counted on PCB to t	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc board , operating temperature and hun Description of revisions DIS-H-00004228 , refer to IEC 60512. st AT:Assurance Test X:Applica	ts before mounten hidity range is app	d on PCB. Designed TS. KUMAZAWA	Approved Checked Designed Drawn	he surface b ransportation Chec SZ. C HS TS. F YK. Y YK. Y ELC	ked NO OKAWA UKUSHIMA AMAGUCHI -374389-0	Da 18. 0 17. 0 17. 0 17. 0	9. 20 2. 14 2. 14 2. 13 2. 13 2. 13
Note 1: Inclu Note 2: No c Note3: Apply t After m Coun Coun Remarks	condensing to the condition o counted on PCB to t	Soldered at solder temperature, 245°c for in immersion , duration, s ature rising by current. f long term storage for unused produc board , operating temperature and hun Description of revisions DIS-H-00004228	ts before mounten hidity range is app	d on PCB. Ilied for interim Designed TS. KUMAZAWA	Approved Checked Designed Drawn	he surface b ransportation Chec SZ. C HS TS. F YK. Y YK. Y ELC	eing immersed. ked NO . OKAWA UKUSHIMA AMAGUCHI AMAGUCHI	Da 18. 0 17. 0 17. 0 17. 0	9. 20 2. 14 2. 14 2. 13 2. 13

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